

**IN THE CLAIMS:**

Please cancel claims 3-12 without prejudice to or disclaimer of the subject matter recited therein.

Please amend claim 1 as follows:

**LISTING OF CURRENT CLAIMS**

Claim 1. (Currently Amended) A thin type BGA semiconductor package comprising:

5 a composite substrate including a wiring board and a dummy die, die having a metal film, wherein the wiring board has an upper surface, a lower surface and an opening, the opening passes through the upper surface and the lower surface, a step is formed in the opening, a plurality of ball pads are formed on the lower surface, a plurality of connecting pads are formed on the step and electrically connect with the ball pads, the dummy die is has a first surface and a second surface, the first surface is attached to the lower surface of the wiring board and  
10 covers covering the opening to form a chip cavity- cavity, the metal film is formed over the second surface of the dummy die;

an integrated circuit chip disposed in the chip cavity, the chip having an active surface and a back surface, a plurality of bonding pads ~~being~~ formed on the active surface and electrically connected to the connecting pads of the wiring board, the  
15 back surface of the chip ~~being~~ attached to the dummy die;

a package body formed in the chip cavity of the composite substrate; and  
a plurality of solder balls on the ball pads.

Claim 2. (Original) The package of claim 1, wherein the dummy die has a thickness smaller than the diameter of the solder balls.

Claims 3-12. (Canceled)